

Full Wafer Test System

Compact Test and Reliability Verification Solution for Logic/Memory/Photonic Devices



SYSTEM BENEFITS

- **Compact Solution for High Throughput Reliability Verification and Test**
 - ◆ Capable of testing thousands of die in a single touchdown
 - ◆ Identifies failing logic/memory/photonic die before final package integration
 - ◆ Integrated system with wafer handling and stepping capabilities
 - ◆ Full-wafer test system using a WaferPakTM contactor and wafer prober available with a high performance thermal chuck for high power wafer requirements
- **Configurable Channel Resources for Full-Wafer Test and Reliability Verification**
 - ◆ Multiple resource modules are available: Universal Channel Modules, High Voltage Channel Modules or High Current Channel Modules
 - ◆ Up to 2,048 "Universal Channel" resources: (I/O / Clock / PPMU / DPS) with deep scan, pattern data and capture memory per channel for test of devices with BIST/DFT
 - ◆ Up to 1,024 high voltage (29 V) or high current (2 A) sources resources
- **Production Proven Full-Wafer Reliability Verification & Test Solution**
 - ◆ Reduces test cost by functionally testing wafer during reliability verification
 - ◆ Compatible with industry standard probers and probe cards
 - ◆ Protects wafers and probe cards with per channel over-current and over-voltage protection

"Setting the Test Standard for Tomorrow"

CORPORATE HEADQUARTERS

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